


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

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|-----------------------------|-----------------------------------------------------------------------------------------------------------------------------------|--------------------------------------|
| 1.1 Company |  | STMicroelectronics International N.V |
| 1.2 PCN No. | MMS/15/9292 | |
| 1.3 Title of PCN | STM32L152V 128K STM32L162 384K STM32L162 512K - dice minor revision | |
| 1.4 Product Category | STM32L1 128K Shrink & STM32L1 384K & STM32L1 512K dice. See full part number list in 9292_Detailed description document attached. | |
| 1.5 Issue date | 2015-12-21 | |

2. PCN Team

| | |
|----------------------------------|---------------------|
| 2.1 Contact supplier | |
| 2.1.1 Name | SETTLES JEFF |
| 2.1.2 Phone | +44 1628896222 |
| 2.1.3 Email | jeff.settles@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Michel BUFFA |
| 2.1.2 Marketing Manager | Daniel COLONNA |
| 2.1.3 Quality Manager | Pascal NARCHE |

3. Change

| | | |
|---------------------|---------------------------------------------|-----------------------------------|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
| Die redesign | Mask or mask set change with new die design | ST Rousset (France) |

4. Description of change

| | Old | New |
|----------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 4.1 Description | <p>Limitations described in erratasheets.</p> <ul style="list-style-type: none"> - Die STM32L1 128K Shrink : revision Z Errata sheet Revision 6 for STM32L1xxx6/8/B-A products - Die STM32L1 384K : revision Y Errata sheets : Revision 2 for STM32L15xxD/C/C-A products, Revision 2 for STM32L162xD/C/C-A products - Die STM32L1 512K : revision A Errata sheets : Revision 3 for STM32L15xxE STM32L15xVD-X products, Revision 3 for STM32L162xE STM32L162VD-X products | <p>ST MCD Division is pleased to announce that the features of STM32L152V 128K & STM32L162 384K & STM32L162 512K products, will be enhanced through the introduction of new dice revisions.</p> <ul style="list-style-type: none"> - Die STM32L1 128K Shrink : Revision Y Changes are described in Errata sheet Revision 7 for STM32L1xxx6/8/B-A products Wake up issues from stop and standby. - Die STM32L1 384K : Revision X Changes are described in Errata sheets : Revision 3 for STM32L15xD/C/C-A products, Revision 3 for STM32L162xD/C/C-A products Wake up issues from stop and standby. - Die STM32L1 512K : Revision Z Changes are described in Errata sheets : Revision 4 for STM32L15xE STM32L15xVD-X products, Revision 4 for STM32L162xE STM32L162VD-X products Wake up issues from stop and standby. |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | Function : changes indicated in Errata sheets | |

5. Reason / motivation for change

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|-----------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 5.1 Motivation | The strategy of ST MCD Division is to increase the robustness and improve performances, quality and functionality of our products. This is achieved by introducing new dice revisions for STM32L152V 128K & STM32L162 384K & STM32L162 512K products. |
| 5.2 Customer Benefit | QUALITY IMPROVEMENT |

6. Marking of parts / traceability of change

| | |
|------------------------|---------------------------------------------------------------------------------------------------------------------------------|
| 6.1 Description | The dice revisions change, see table in 9292_Detailed description document attached. It is marked onto the package of the part. |
|------------------------|---------------------------------------------------------------------------------------------------------------------------------|

| 7. Timing / schedule | |
|-------------------------------------|--------------|
| 7.1 Date of qualification results | 2016-02-21 |
| 7.2 Intended start of delivery | 2016-03-21 |
| 7.3 Qualification sample available? | Upon Request |

| 8. Qualification / Validation | | | |
|----------------------------------------------------|------------------------------------------|------------|------------|
| 8.1 Description | 9292_reliability plan_429Y_436X_437Z.pdf | | |
| 8.2 Qualification report and qualification results | Available (see attachment) | Issue Date | 2015-12-21 |

| 9. Attachments (additional documentations) |
|------------------------------------------------------------------------------------------------|
| 9292PpPrdtLst.pdf 9292_Detailed description.pdf 9292_reliability plan_429Y_436X_437Z.pdf |

| 10. Affected parts | | |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current | | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No |
| | STM32L151RET6 | |
| | STM32L151VDT6 | |
| | STM32L151ZCT6 | |
| | STM32L152VDT6 | |
| | STM32L151VET6 | |

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